



PATENTS

#61B  
Amend  
1600  
6-2-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Hidemitsu AOKI et al.

Confirmation No. 6696

Serial No. 09/715,000

GROUP 2825

Filed November 20, 2000

Examiner Chuong A. Luu

IMPROVED SEMICONDUCTOR WAFER  
SURFACE AND METHOD OF TREATING  
A SEMICONDUCTOR WAFER SURFACE

AMENDMENT

Commissioner for Patents

Washington, D.C. 20231

Sir:

Responsive to the Official Action of February 28, 2002,  
please amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 3, replace the paragraph, beginning on line 11, as  
follows:

B1  
--In accordance with the above conventional processes,  
the semiconductor wafer 1 is exposed to an air or an atmosphere  
after the semiconductor wafer 1 is unloaded from the cleaning  
apparatus and before the semiconductor wafer 1 is loaded into the  
growth chamber. A time duration between after the semiconductor  
wafer 1 is unloaded from the cleaning apparatus and before the  
semiconductor wafer 1 is loaded into the growth chamber depends  
upon a waiting time for loading the semiconductor wafer into the  
growth chamber. The waiting time may be, actually, for example,  
one day or more.--.

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